

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJQ08N03
Package Type :	SOP8

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.3875%
Lead Frame	Cu	7440-50-8	97.03%	45.4213%
	Fe	7439-89-6	2.21%	
	Pb	7439-92-1	0.01%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.02%	
	Ag	7440-22-4	0.66%	
Epoxy	Silver	7440-22-4	80.00%	0.5651%
	bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight ≤ 700) (old)	9003-36-5	12.00%	
	1,4-bis(2,3	2425-79-8	6.50%	
	dapsone	80-08-0	1.50%	
Wire	copper	7440-50-8	99.99%	0.3337%
	others	/	0.01%	
Mold Compound	Epoxy Resin1	Trade	6.80%	51.0505%
	Epoxy Resin2	Trade	4.70%	
	Phenol Resin	Trade	5.30%	
	Carbon Black	1333-86-4	0.20%	
	Amorphous silica	60676-86-0	83.00%	
Plating	Tin	7440-31-5	100.00%	2.242%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.